SWITCHMODE Soft Ultrafast Recovery Reverse Polarity Power Rectifier

State-of-the-art geometry features epitaxial construction with glass passivation. Ideally suited for low voltage, high frequency switching power supplies, free wheeling diode and polarity protection diodes.

Features

- Soft Ultrafast Recovery
- Matched Dual Die Construction May Be Paralleled for High Current Output
- Short Heat Sink Tab Manufactured Not Sheared
- Epoxy Meets UL 94 V-0 @ 0.125 in.
- AEC-Q101 Qualified and PPAP Capable
- SSRD8 Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements
- All Packages are Pb-Free*

Mechanical Characteristics

- Case: Epoxy, Molded
- Weight: 0.4 Grams (Approximately)
- Finish: All External Surfaces Corrosion Resistant and Terminal Leads are Readily Solderable
- Lead and Mounting Surface Temperature for Soldering Purposes: 260°C Max. for 10 Seconds
- ESD Ratings:
 - ♦ Machine Model = C
 - ♦ Human Body Model = 2



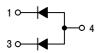
ON Semiconductor®

http://onsemi.com

SOFT ULTRAFAST REVERSE POLARITY RECTIFIER 6.0 AMPERES, 200 VOLTS



DPAK CASE 369C



MARKING DIAGRAM



A = Assembly Location

= TEal

WW = Work Week

G = Pb-Free Package

ORDERING INFORMATION

Device	Package	Shipping [†]
MSRD620CTRG	DPAK (Pb-Free)	75 Units/Rail
SSRD8620CTRG	DPAK (Pb-Free)	75 Units/Rail
MSRD620CTT4RG	DPAK (Pb-Free)	2,500 / Tape & Reel
SSRD8620CTT4RG	DPAK (Pb-Free)	2,500 / Tape & Reel

[†]For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

^{*}For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

MAXIMUM RATINGS

Rating	Symbol	Value	Unit
Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage	V _{RRM} V _{RWM} V _R	200	V
Average Rectified Forward Current (At Rated V _R , T _C = 162°C) Per Leg Per Package	I _O	3.0 6.0	А
Non-Repetitive Peak Surge Current (Surge Applied at Rated Load Conditions, Halfwave, Single Phase, 60 Hz) Per Package	I _{FSM}	45	A
Storage/Operating Case Temperature	T _{stg,} T _c	-65 to +175	°C
Operating Junction Temperature	TJ	-65 to +175	°C

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

THERMAL CHARACTERISTICS

Rating	Symbol	Value	Unit
Thermal Resistance – Junction–to–Case (Note 1) Per Leg	$R_{ heta JC}$	5.0	°C/W
Thermal Resistance – Junction–to–Ambient (Note 1) Per Leg	$R_{ hetaJA}$	60	°C/W
Thermal Resistance – Junction–to–Ambient (Note 2) Per Leg	$R_{ heta JA}$	166	°C/W

^{1.} Mounted with 700 mm² copper pad size (approximately 1 in²) 1 oz FR4 board.

ELECTRICAL CHARACTERISTICS

Rating	Symbol	Va	lue	Unit
Maximum Instantaneous Forward Voltage (Note 3)	V _F	T _J = 25°C	T _J = 125°C	V
Per Leg (I _F = 3.0 A) (I _F = 6.0 A)		1.15 1.30	0.95 1.15	
Maximum Instantaneous Reverse Current (Note 3) Per Leg	I _R	T _J = 25°C	T _J = 125°C	μΑ
(V _R = 200 V)		1.0	200	
Maximum Reverse Recovery Time (Note 4) Per Leg (V _B = 30 V, I _F = 1.0 A, di/dt = 50 A/μs)	t _{rr}	7	'5	ns

^{3.} Pulse Test: Pulse Width ≤ 380 µs, Duty Cycle ≤ 2%.

^{2.} Mounted with pad size approximately 46 mm² copper, 1 oz FR4 board.

^{4.} t_{rr} measured projecting from 25% of I_{RM} to ground.

TYPICAL CHARACTERISTICS

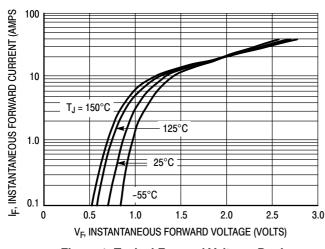


Figure 1. Typical Forward Voltage, Per Leg

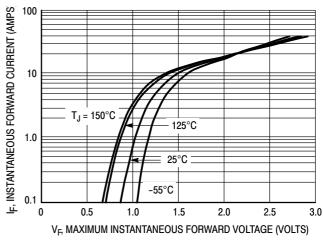


Figure 2. Maximum Forward Voltage, Per Leg

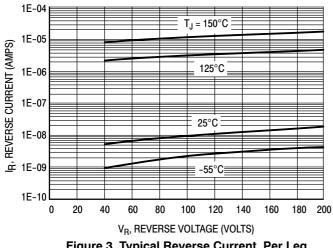


Figure 3. Typical Reverse Current, Per Leg

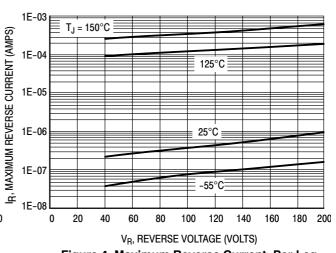


Figure 4. Maximum Reverse Current, Per Leg

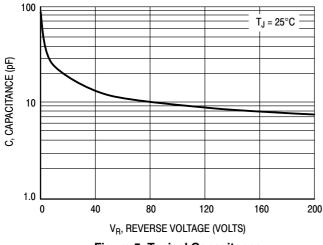


Figure 5. Typical Capacitance

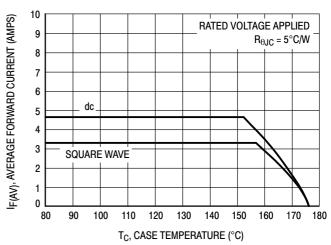


Figure 6. Typical Current Derating, Case (Per Leg)

TYPICAL CHARACTERISTICS

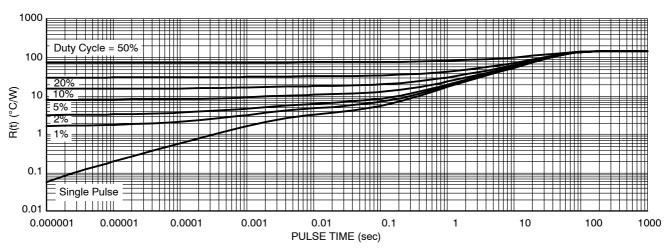


Figure 7. Thermal Response, Junction-to-Ambient (46 mm² pad)

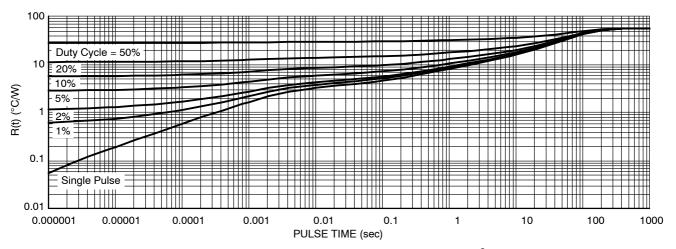
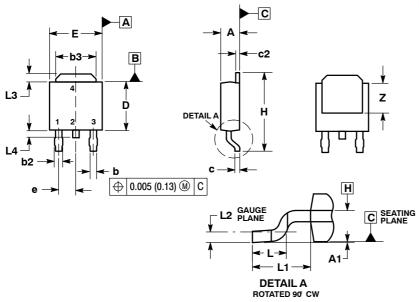


Figure 8. Thermal Response, Junction-to-Ambient (1 in² pad)

PACKAGE DIMENSIONS

DPAK (SINGLE GAUGE)

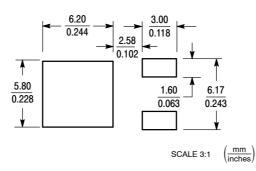
CASE 369C-01 ISSUE D



- 1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994
- 2. CONTROLLING DIMENSION: INCHES.
 3. THERMAL PAD CONTOUR OPTIONAL WITHIN DI-
- MENSIONS b3, L3 and Z.
 4. DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH, PROTRUSIONS, OR BURRS. MOLD FLASH, PROTRUSIONS, OR GATE BURRS SHALL NOT EXCEED 0.006 INCHES PER SIDE.
 5. DIMENSIONS D AND E ARE DETERMINED AT THE
- OUTERMOST EXTREMES OF THE PLASTIC BODY.
- 6. DATUMS A AND B ARE DETERMINED AT DATUM

	INCHES		MILLIMETERS		
DIM	MIN	MAX	MIN	MAX	
Α	0.086	0.094	2.18	2.38	
A1	0.000	0.005	0.00	0.13	
b	0.025	0.035	0.63	0.89	
b2	0.030	0.045	0.76	1.14	
b3	0.180	0.215	4.57	5.46	
С	0.018	0.024	0.46	0.61	
c2	0.018	0.024	0.46	0.61	
D	0.235	0.245	5.97	6.22	
E	0.250	0.265	6.35	6.73	
е	0.090	0.090 BSC		2.29 BSC	
Н	0.370	0.410	9.40	10.41	
L	0.055	0.070	1.40	1.78	
L1	0.108 REF		2.74 REF		
L2	0.020 BSC		0.51 BSC		
L3	0.035	0.050	0.89	1.27	
L4		0.040		1.01	
Z	0.155		3.93		

SOLDERING FOOTPRINT*



*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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